ABSTRACT

semiconductor chip mounting component includes Α support structure having a top surface, a bottom surface, and a gap extending through the support structure between the surfaces for defining first and second portions of the support The component includes a plurality of electrically structure. each lead having a connection conductive leads, extending across the gap, the connection section having a first end disposed on the support structure on one side of the gap, a second end secured to the support structure on an The opposite side of the gap and a frangible section. least one elongated includes at mounting component disposed alongside the gap on one of the first and second portions of the support structure, wherein each of the leads extends across the gap and is connected to the bus, wherein the leads are adapted to be bonded to contacts on a semiconductor chip by breaking the frangible sections of the leads so as to disconnect the leads from the bus.